

VS-ETU1506S-M3, VS-ETU1506-1-M3

Vishay Semiconductors

Ultrafast Rectifier, 15 A FRED Pt[®]

2 3 D²PAK (TO-263AB) **TO-262AA** Base cathode n^2 02 93 3 \frown N/C N/C Anode Anode VS-ETU1506S-M3 VS-ETU1506-1-M3

PRIMARY CHARACTERISTICS							
I _{F(AV)}	15 A						
V _R	600 V						
V _F at I _F	1.1 V						
t _{rr} (typ.)	24 ns						
T _J max.	175 °C						
Package	D ² PAK (TO-263AB), TO-262AA						
Circuit configuration	Single						

FEATURES

- · Low forward voltage drop
- · Ultrafast recovery time
- 175 °C operating junction temperature
- Low leakage current
- Designed and qualified according to JEDEC[®]-JESD 47
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

State of the art, ultralow V_F, soft-switching ultrafast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units, and DVD AC/DC power supplies.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	V _{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 143 °C	15	^			
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	160				
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-	V	
E	V _F	I _F = 15 A	-	1.35	1.9	V	
Forward voltage		I _F = 15 A, T _J = 150 °C	-	1.1	1.3		
Reverse leakage current	I _R	$V_{R} = V_{R}$ rated	-	0.01	15		
Reverse leakage current		$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	20	200	μA	
Junction capacitance	CT	V _R = 600 V	-	12	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH	

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DYNAMIC RECOVERY	CHARACTEF	RISTICS ($T_J = 25$	5 °C unless otherw	ise speci	fied)		
PARAMETER	SYMBOL	TEST CC	MIN.	TYP.	MAX.	UNITS	
		$I_F = 1 \text{ A}, dI_F/dt = 1$	00 A/µs, V _R = 30 V	-	24	28	
Reverse recovery time	+	I _F = 15 A, dI _F /dt =	100 A/µs, V _R = 30 V	-	36	47	ns
Reverse recovery lime	t _{rr}	T _J = 25 °C		-	40	-	115
		T _J = 125 °C	I _F = 15 A dI _F /dt = 200 A/μs V _R = 390 V	-	87	-	
Peak recovery current	l	T _J = 25 °C		-	5	-	- A
Feak recovery current	IRRM	T _J = 125 °C		-	9.0	-	
Reverse recovery charge	0	T _J = 25 °C		-	107	-	C
neverse recovery charge	Q _{rr}	T _J = 125 °C		-	430	-	C
Reverse recovery time	t _{rr}		I _F = 15 A	-	53	-	ns
Peak recovery current	I _{RRM}	T _J = 125 °C	dI _F /dt = 800 A/µs	-	25	-	А
Reverse recovery charge	Q _{rr}		V _R = 390 V	-	730	-	nC

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C		
Thermal resistance, junction-to-case	R _{thJC}		-	1.3	1.51	°C/W		
Thermal resistance, junction-to-ambient	R _{thJA}	Typical socket mount	-	-	70			
Thermal resistance, case-to-heat sink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-			
Waight			-	2.0	-	g		
Weight			-	0.07	-	oz.		
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)		
Marking davias		Case style D ² PAK (TO-263AB)	ETU1506S					
Marking device		Case style TO-262		ETU1	506-1			



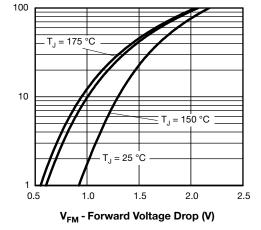


Fig. 1 - Typical Forward Voltage Drop Characteristics

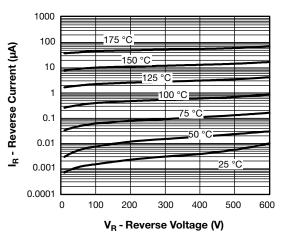


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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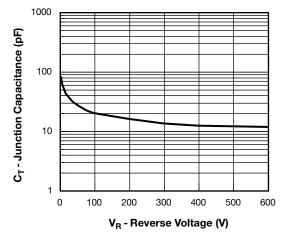


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

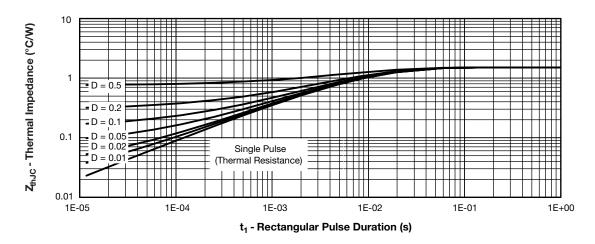


Fig. 4 - Max. Thermal Impedance ZthJC Characteristics

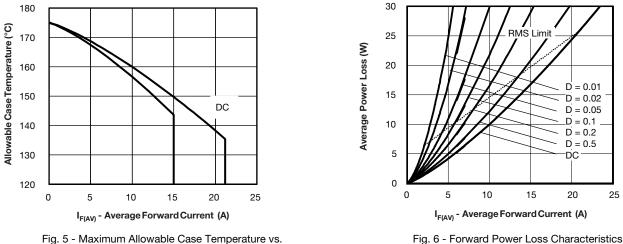


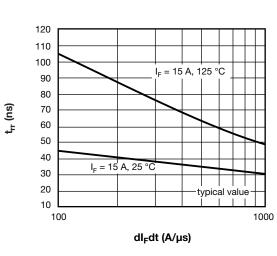
Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

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Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

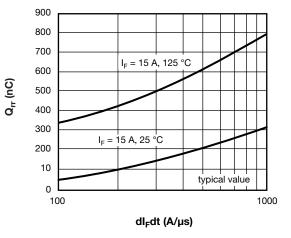


Fig. 8 - Typical Stored Charge vs. dl_F/dt

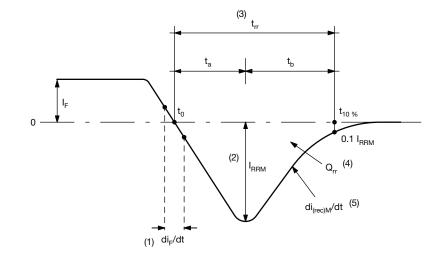


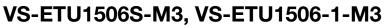
Fig. 9 - Reverse Recovery Waveform and Definitions

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ORDERING INFORMATION TABLE

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Device code	VS-	E	т	U	15	06	S	TRL	-M3	
	1	2	3	4	5	6	7	8	9	
	1		nay Sem			oduct				
	2 -		uit conf		1					
	3 -	• T=	TO-220							
	4	- U =	ultrafas	t recove	ery time					
	5 -	- Cur	rent cod	le (15 =	15 A)					
	6		tage coc	•						
	7		= D ² PAI		63AB)					
			= TO-20							
	8		one = tu							
	-		•		•					B) package)
	-	- • TF	RR = tap	e and re	eel (righ	t oriente	ed, for [D ² PAK	(TO-263	BAB) package
	9	M3	s = halog	gen-free	, RoHS-	complia	ant, and	l termin	ations le	ead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-ETU1506S-M3	50	Antistatic plastic tubes					
VS-ETU1506STRR-M3	800	13" diameter plastic tape and reel					
VS-ETU1506STRL-M3	800	13" diameter plastic tape and reel					
VS-ETU1506-1-M3	50	Antistatic plastic tubes					

LINKS TO RELATED DOCUMENTS							
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164					
	TO-262AA	www.vishay.com/doc?96165					
Dant mandring information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444					
Part marking information	TO-262AA	www.vishay.com/doc?95443					
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?96424					
SPICE model		www.vishay.com/doc?96132					

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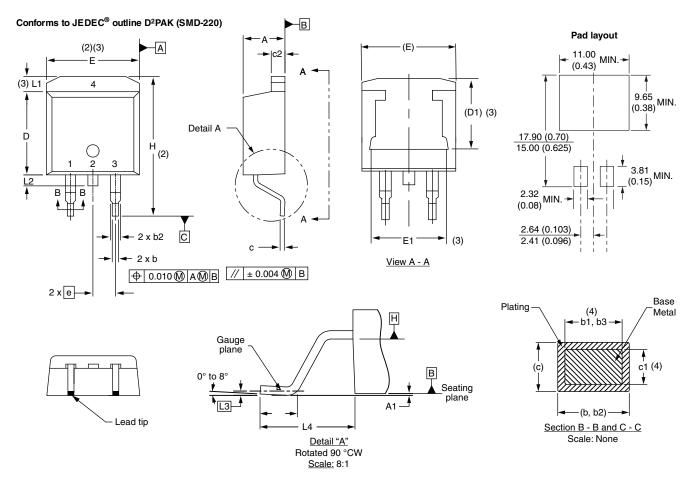


Outline Dimensions

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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL MILL	MILLIM	LIMETERS IN		INCHES			SYMBOL		MILLIMETERS		INCHES	
STMBUL	MIN.	MAX.	MIN.	MAX.	NOTES	STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
А	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5 M-1994

(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

(3) Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only

⁽⁵⁾ Datum A and B to be determined at datum plane H

⁽⁶⁾ Controlling dimension: inches

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-263AB

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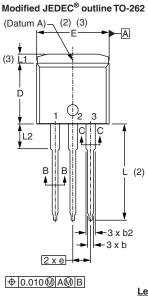


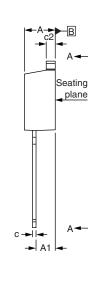
Outline Dimensions

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TO-262AA

DIMENSIONS in millimeters and inches



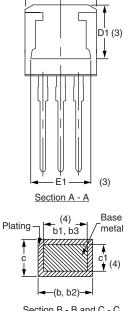


Lead assignments

Lead tip



1. - Anode (two die)/open (one die) 2., 4. - Cathode 3. - Anode



F

Section B - B and C - C Scale: None

SYMBOL	MILLIN	IETERS	INC	NOTEO	
	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	BSC	0.100) BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

Notes

 (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body (3)

Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only (5)

Controlling dimension: inches Outline conform to JEDEC[®] TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), (6) L1 (max.), L2 (min., max.)

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